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Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
T	0.78mm +/-0.20mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

General Information	
Series	SMD Comm COG Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3.3 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	+/-0.5 pF
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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